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(12) **United States Design Patent**  
**Phillips et al.**

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(54) **SENSOR MODULE**

(71) Applicant: **Samsung Electronics Co., Ltd.**,  
Suwon-si (KR)

(72) Inventors: **Sheldon George Phillips**, Glendale, CA  
(US); **Frank Nuovo**, Los Angeles, CA  
(US); **Joseph J. Kopp, Jr.**, Fairfield, CA  
(US); **Tom Torfs**, Kraainem (BE)

(73) Assignee: **Samsung Electronics Co., Ltd.**,  
Suwon-si (KR)

(\*\*) Term: **14 Years**

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(52) **U.S. Cl.**  
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(58) **Field of Classification Search**  
CPC ..... G08G 1/096883; G08G 1/096872;  
G08G 1/096775; G01C 21/16; G01C 21/3688;  
G01C 21/30; G01V 8/20; G01J 5/02; G01J  
5/023; G01J 5/24; G01J 5/10; G01J 5/20;  
G01J 5/0235; G01J 5/08; G01J 5/0853;  
G01J 5/33; G01J 5/34  
USPC ..... D10/30-39, 65, 70, 78, 97, 98; D11/3;  
D13/173-177; D14/138 R, 203.5, 247,  
D14/338-340, 344, 346, 347; D24/167, 168  
See application file for complete search history.

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*Primary Examiner* — Antoine D Davis

(74) *Attorney, Agent, or Firm* — McAndrews Held & Malloy, Ltd.

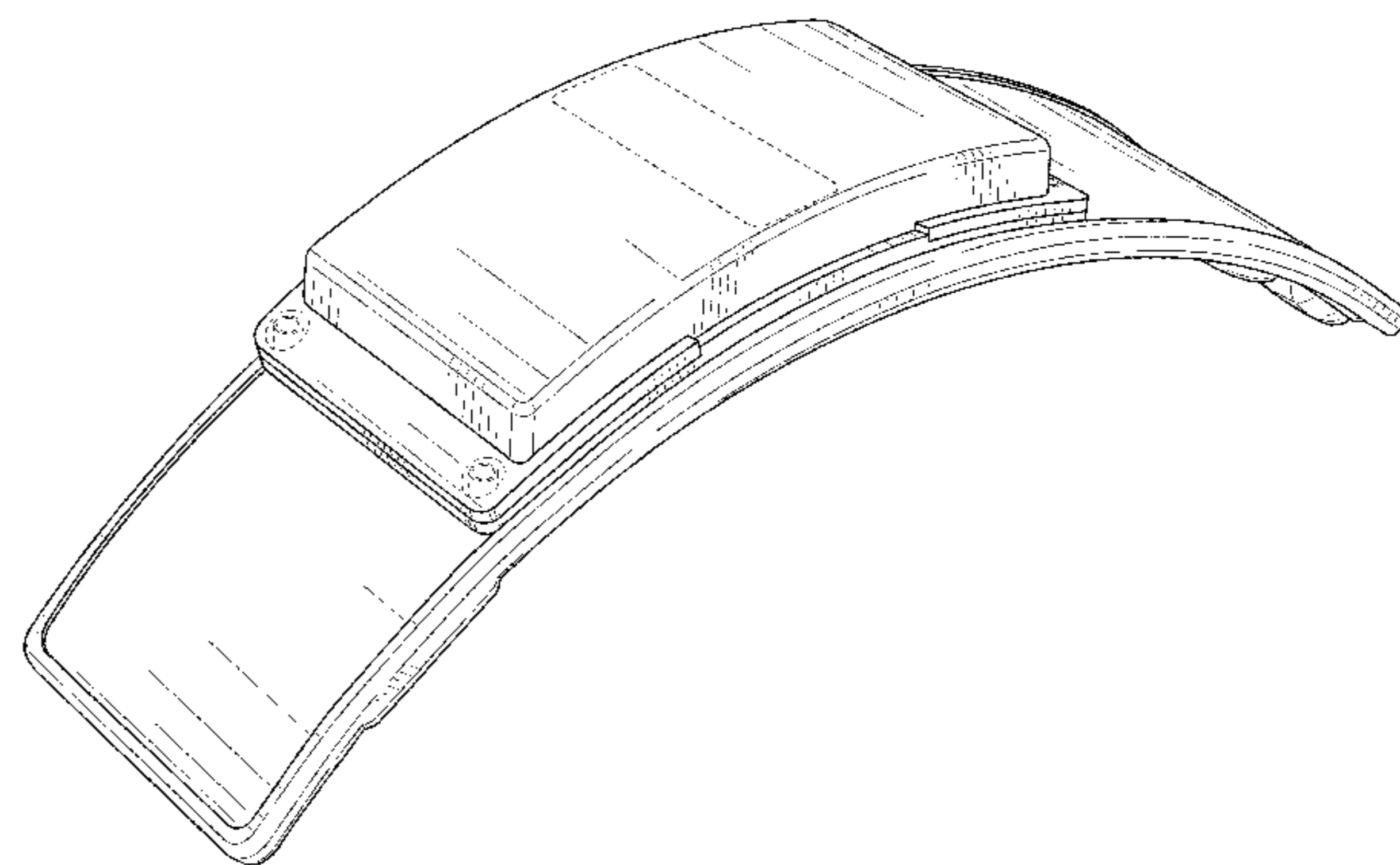
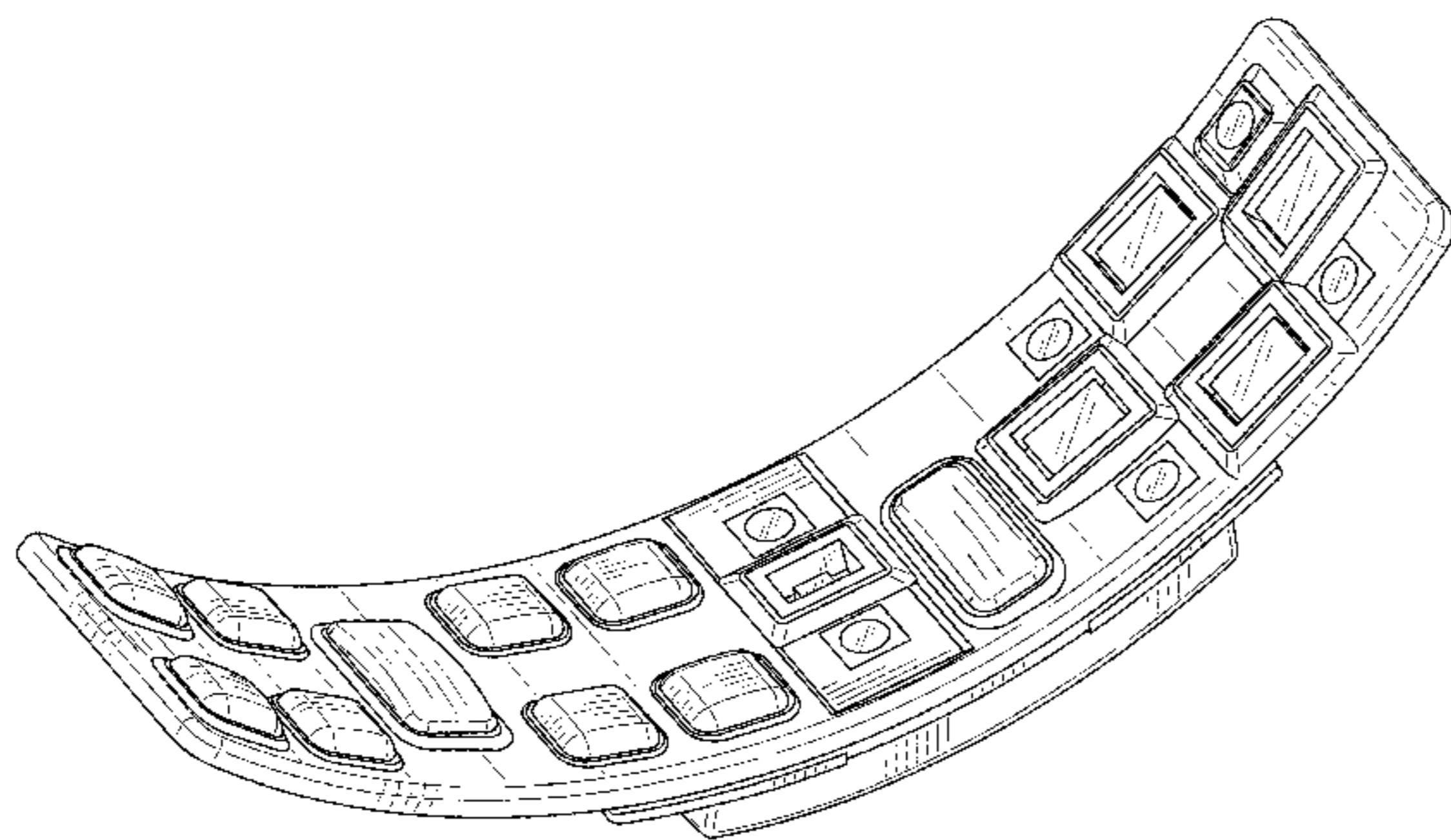
(57) **CLAIM**

The ornamental design for a sensor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a top left front perspective view of a sensor module showing our new design;  
FIG. 2 is a rear elevation view thereof;  
FIG. 3 is a front elevation view thereof;  
FIG. 4 is a right side elevation view thereof;  
FIG. 5 is a left side elevation view thereof;  
FIG. 6 is a top plan view thereof;  
FIG. 7 is a bottom plan view thereof; and,  
FIG. 8 is a bottom right rear perspective view thereof.  
The dashed broken lines are for environmental purposes only and form no part of the claimed design.  
Any views of the sensor module that are not shown in the figures form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



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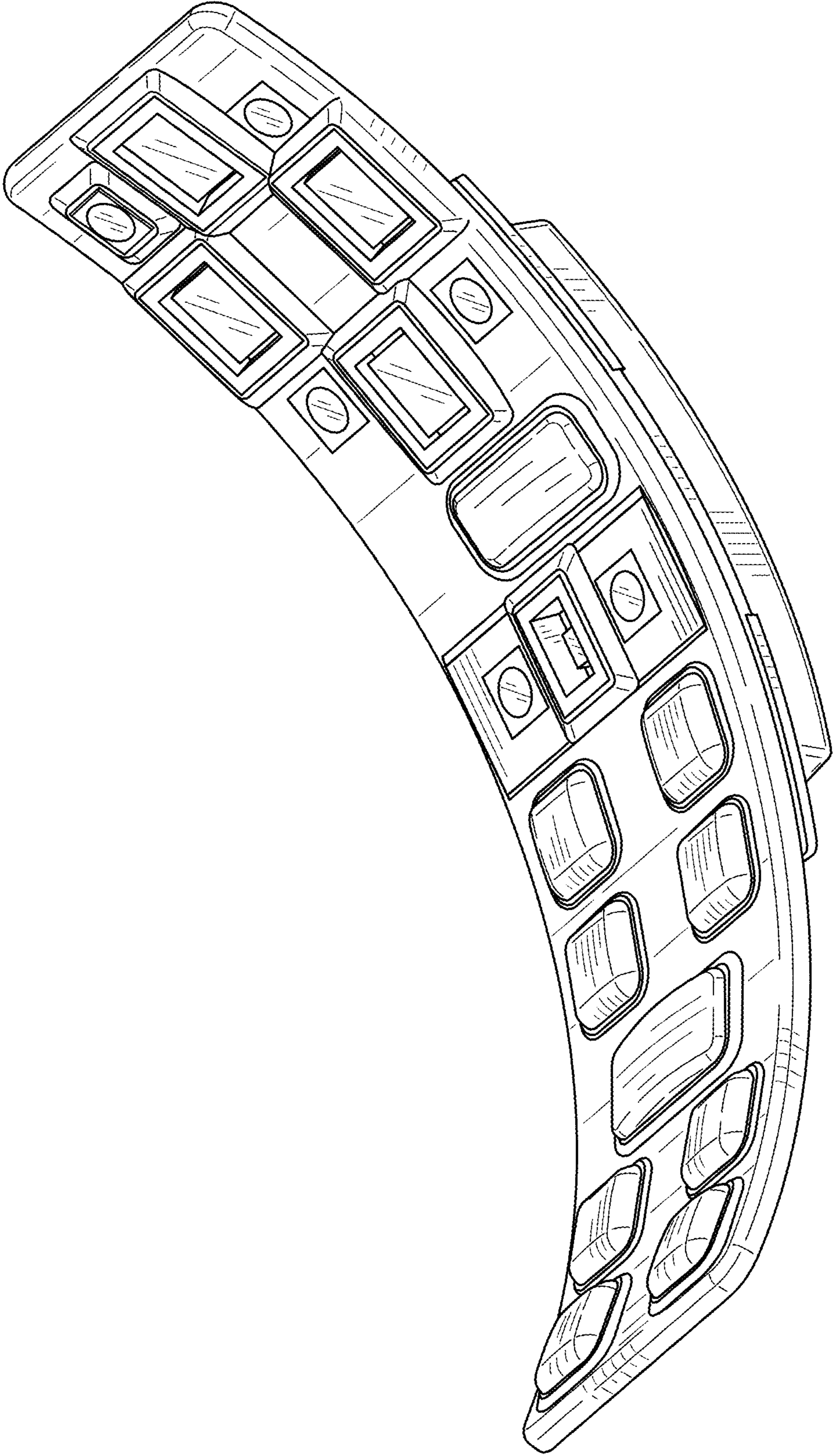


FIG. 1

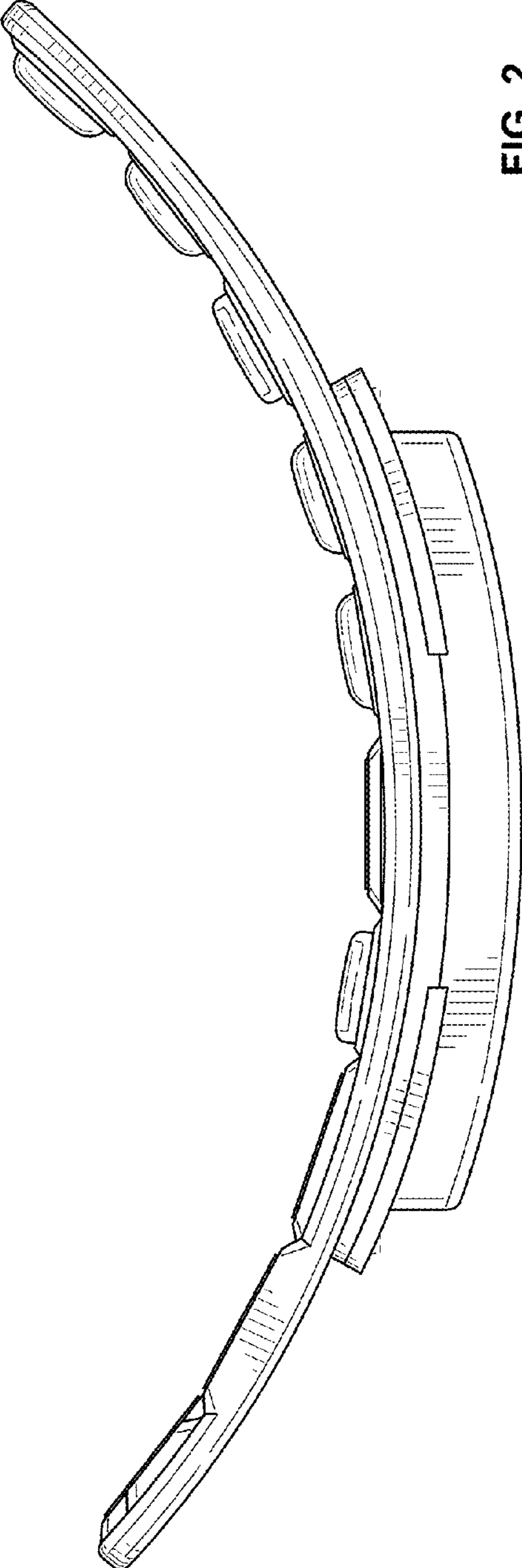


FIG. 2

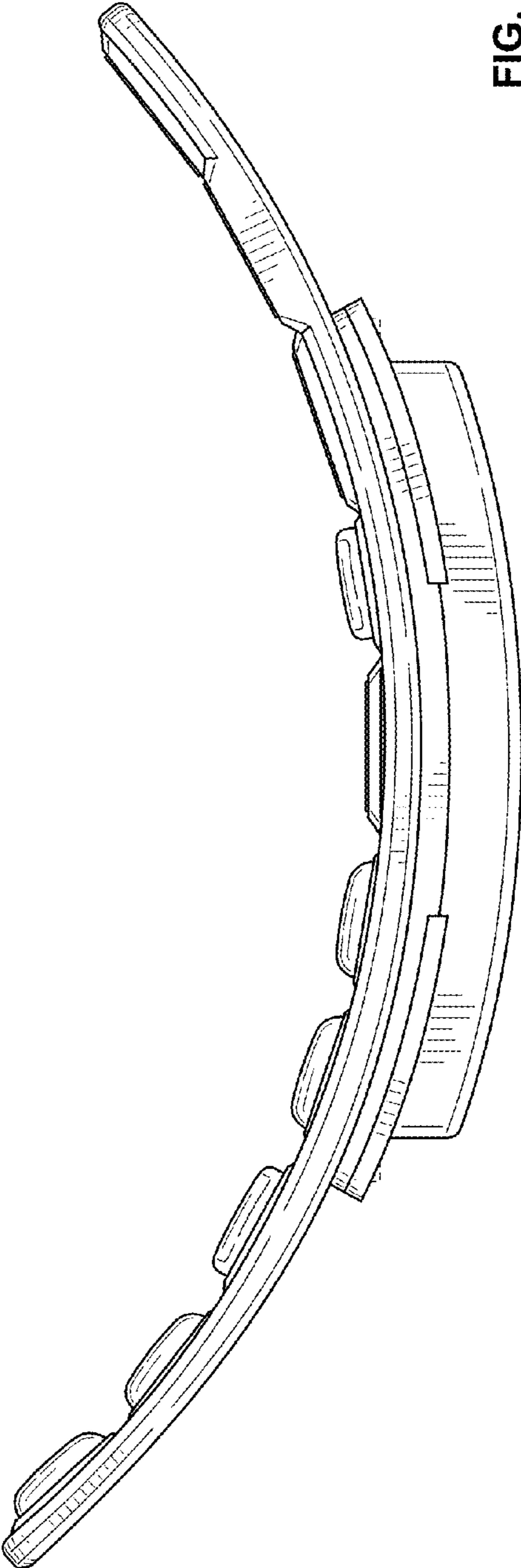


FIG. 3

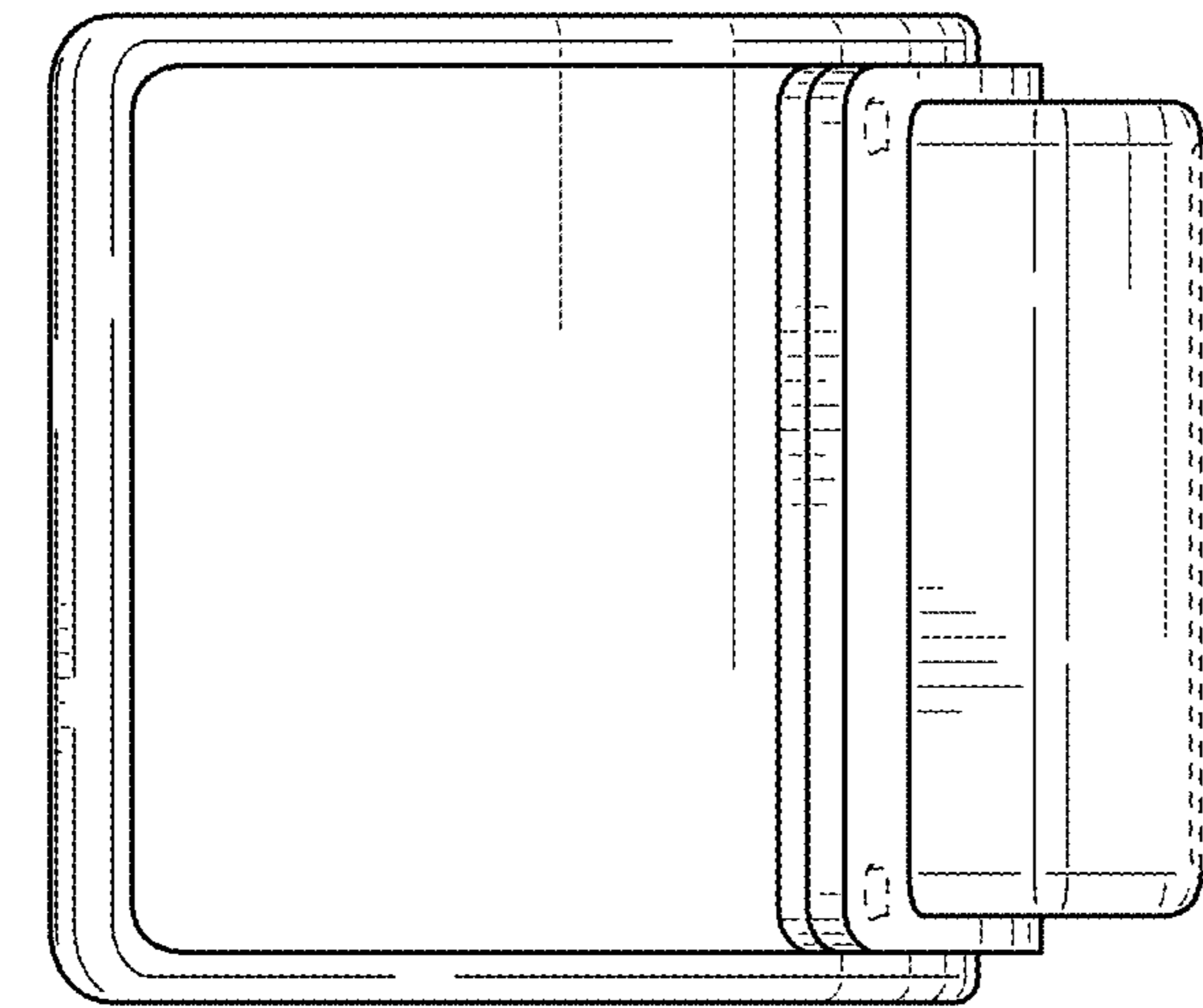


FIG. 5

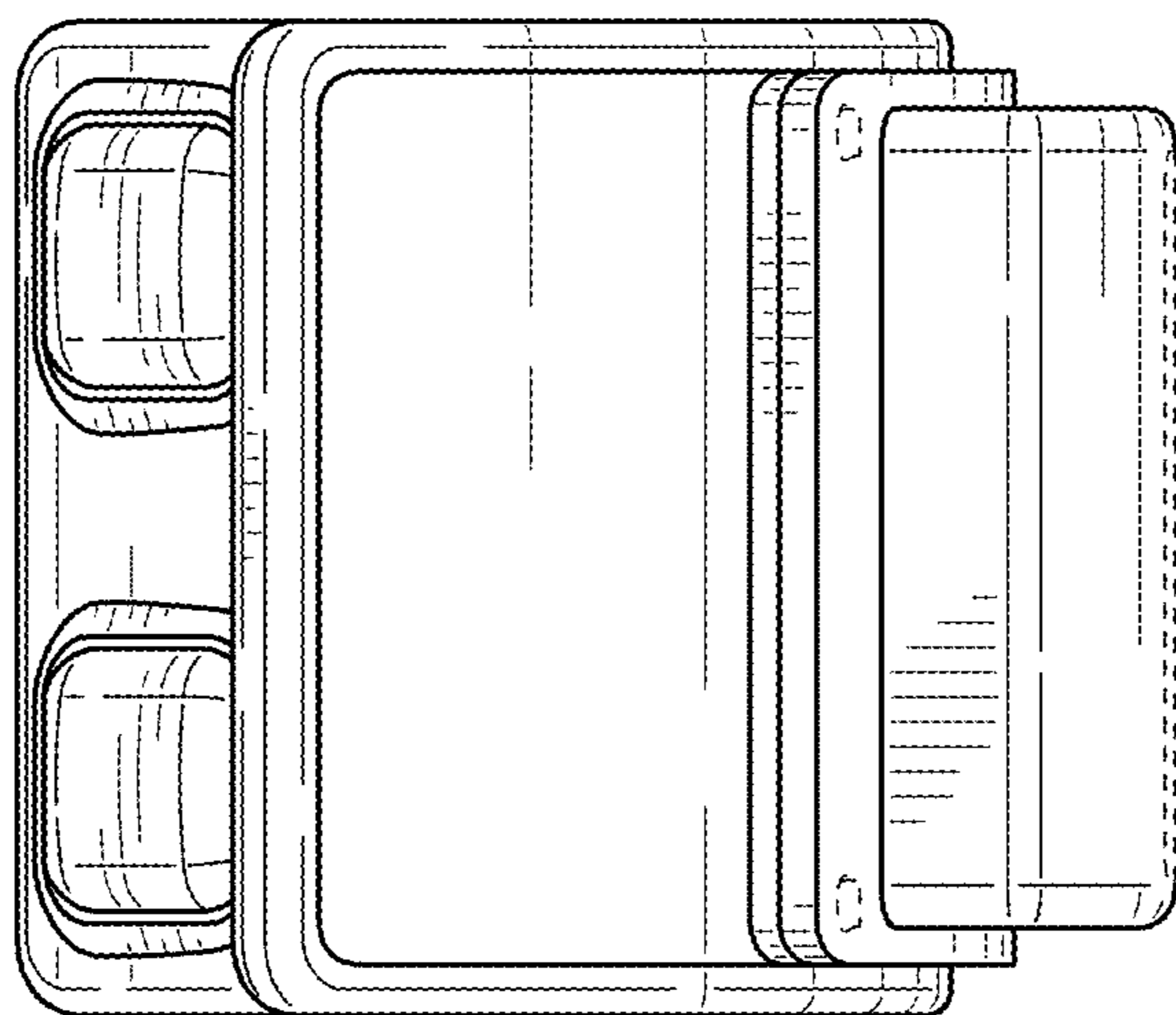


FIG. 4

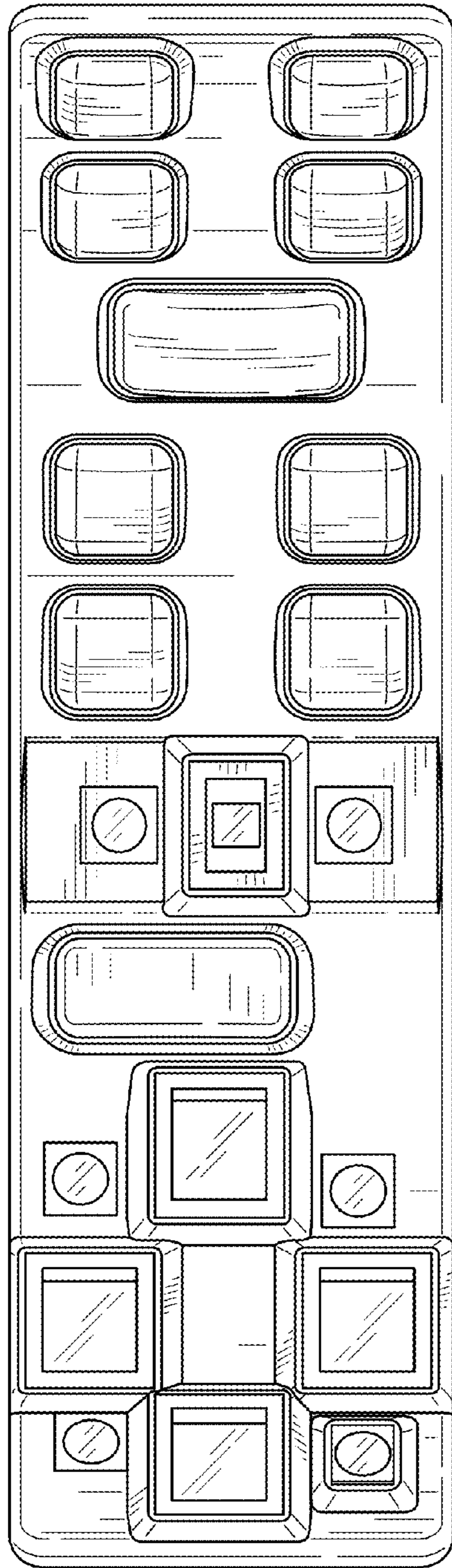


FIG. 6

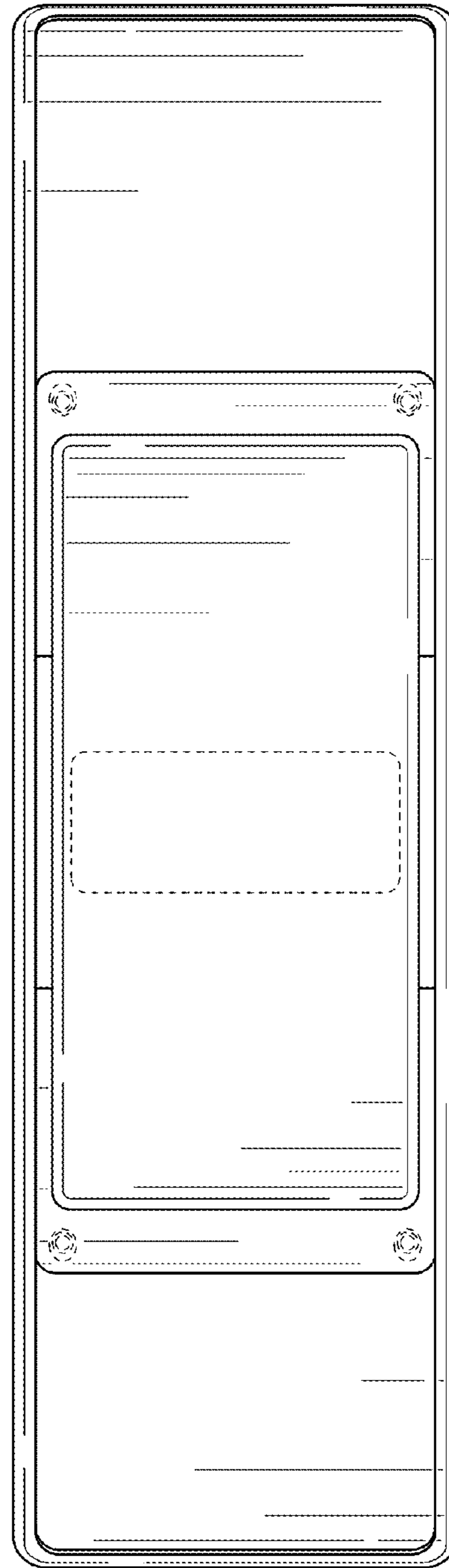


FIG. 7

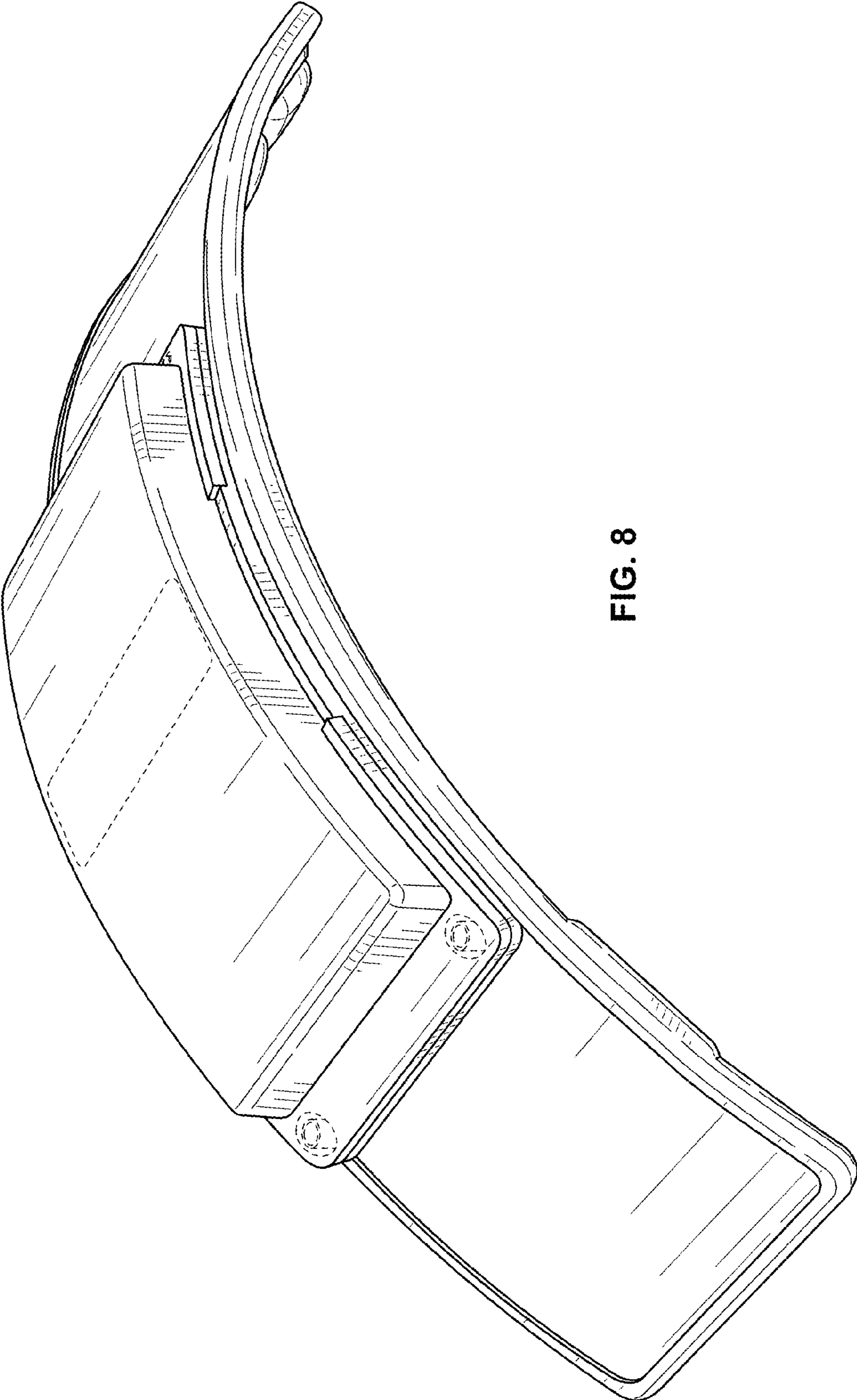


FIG. 8